

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Sing Lon Wu	08/08/2005
Chung Hsien Hsin	08/08/2005
RECEIVING PARTY DATA	
Name:	Kingpak Technology Inc.
Street Address:	No. 84, Taiho Rd., Chupei
City:	Hsinchu Hsien
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11213256
CORRESPONDENCE DATA	
Fax Number:	(408)996-8625
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	408-255-4976
Email:	linyun@pacbell.net
Correspondent Name:	Lin-Yun Cheng
Address Line 1:	20775 Norada Ct.
Address Line 4:	Saratoga, CALIFORNIA 95070
NAME OF SUBMITTER:	Lin-Yun Cheng
Total Attachments: 1 source=assignment#page1.tif	

OP \$40.00 11213256

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration, ASSIGNOR

Assignor's Name	Assignor's Residence and/or Address	Nationality
(1) Sing Lon Wu	No.84 , Taiho Road , Chupei , Hsinchu Hsien , Taiwan	Taiwan
(2) Chung Hsien HSIN	No.84 , Taiho Road , Chupei , Hsinchu Hsien , Taiwan	Taiwan
(3)		
(4)		

hereby sells, assigns and transfers to ASSIGNEE

Assignee's Name	Assignee's Residence and/or Address	Nationality
Kingpak Technology Inc.	No.84 , Taiho Road , Chupei , Hsinchu Hsien , Taiwan	Taiwan

and the successors, assigns and legal representatives of the ASSIGNEE *[check one of the following]*

< the entire right, title, and interest < an undivided _____ percent (_____ %) interest

in and to any and all improvements which are disclosed in the invention entitled: METHOD FOR RE-FORMING

AN IMAGE SENSOR

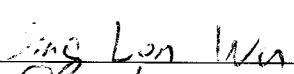

, and which is found in *[check one of the following]*

- (a) U.S. patent application executed on 8.8.2005
- (b) U.S. patent application serial number 11/213,256, filed on 08/26/2005
- (c) < U.S. patent number _____, issued on _____

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute thereof, and as to Letters Patent any reissued or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNOR will communicate to ASSIGNEE or its representatives any facts known to ASSIGNOR respecting the invention, to testify in any legal proceedings, to sign all lawful papers, to execute all divisions, continuations, substitutions, renewal and reissue applications, and to generally do those things necessary to aid ASSIGNEE and its successors and assigns to obtain and enforce proper protection for the invention in the United States and in any and all foreign countries.

Assignor's Signature	Printed Name and/or Title	Date Signed
(1) 	Sing Lon Wu	<u>8/8/05</u>
(2) 	Chung Hsien HSIN	<u>8/8/05</u>
(3)		
(4)		

PATENT